



VERSION WITH MARKINGS TO SHOW CHANGES MADE

*RECEIVED
SEP 23 2002
INCLG CTR 2800*

THE CLAIMS:

Claim 1 has been amended as follows:

- 5 1. (Twice Amended) A packaging structure of an image sensor, comprising:

 a substrate including a plurality of straight metal sheets directly penetrating through the substrate, glue for sealing the metal sheets after the metal sheets are formed, a first surface having a periphery, and a second surface opposite to the first surface, the metal sheets being exposed to the outside via the first surface and the second surface to form first contacts and second contacts, respectively;

 a projecting edge provided on the periphery of the first surface of the substrate to form a concavity above the substrate;

 an image sensing chip mounted on the substrate and within the concavity, a plurality of bonding pads being formed on the image sensing chip;

15 a plurality of wirings electrically and directly connecting the bonding pads of the image sensing chip to the first contacts of the first surface of the substrate in order to electrically connect the image sensing chip to the substrate, so that electrical signals from the image sensing chip are capable of being transmitted to the second contacts of the second surface of the substrate; and

20 a transparent layer arranged on the projecting edge on the first surface of the substrate so that the image sensing chip is capable of receiving optical signals.

Claim 6 has been amended as follows:

- 25 6. (Twice Amended) A method for packing an image sensor, comprising the steps of:

 preparing a substrate including a plurality of straight metal sheets directly

penetrating through the substrate, glue for sealing the metal sheets after the metal sheets are formed, a first surface having a periphery, and a second surface opposite to the first surface, the metal sheets being exposed to the outside via the first surface and the second surface to form first contacts and second contacts,
5 respectively;

providing a projecting edge on the periphery of the first surface of the substrate to form a concavity above the substrate;

mounting an image sensing chip having a plurality of bonding pads onto the first surface of the substrate and within the concavity;

10 directly connecting the bonding pads of the image sensing chip to the first contacts of the first surface of the substrate by a plurality of wirings; and

mounting a transparent layer on the projecting edge located on the first surface of the substrate in order to cover the image sensing chip.